

MC12093

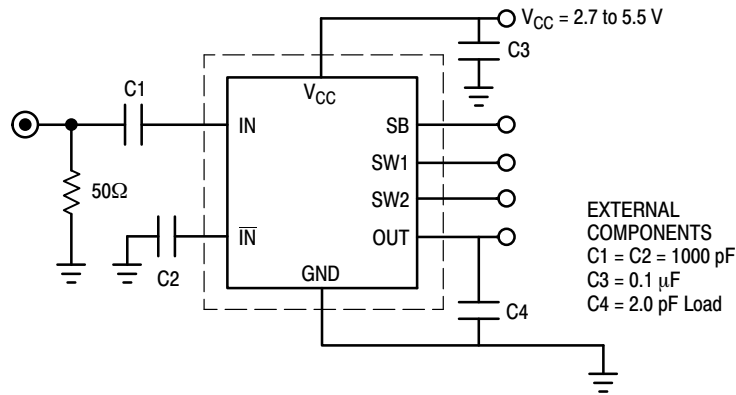


Figure 2. AC Test Circuit

Table 2. ATTRIBUTES

Characteristics	Value	
Internal Input Pulldown Resistor	N/A	
Internal Input Pullup Resistor	N/A	
ESD Protection Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV	
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb Pkg	Pb-Free Pkg
SOIC-8 DFN8	Level 1 Level 1	Level 1 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
Transistor Count	125 Devices	
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Rating	Value	Unit
V _{CC}	Power Supply Voltage, Pin 2	−0.5 to 6.0	Vdc
T _A	Operating Temperature Range	−40 to 85	°C
T _{stg}	Storage Temperature Range	−65 to 150	°C
I _O	Maximum Output Current, Pin 4	4.0	mA
θ _{JC}	Thermal Resistance (Junction-to-Case) (Note 2) DFN8	35 to 40	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

NOTE: ESD data available upon request.

2. JEDEC standard multilayer board – 2S2P (2 signal, 2 power). For DFN8 only, thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

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Table 4. ELECTRICAL CHARACTERISTICS ($V_{CC} = 2.7$ to 5.5 V; $T_A = -40$ to 85°C)

Symbol	Characteristic	Min	Typ	Max	Unit
f_t	Toggle Frequency (Sine Wave)	0.1	1.4	1.1	GHz
I_{CC}	Supply Current	–	3.0	4.5	mA
ISB	Stand-By Current	–	120	200	μA
V_{IH1}	Stand-By Input HIGH (SB)	2.0	–	V_{CC}	V
V_{IL1}	Stand-By Input LOW (SB)	Gnd	–	0.8	V
V_{IH2}	Divide Ratio Control Input HIGH (SW1 & SW2)	$V_{CC} - 0.5$	V_{CC}	$V_{CC} + 0.5$	V
V_{IL2}	Divide Ratio Control Input LOW (SW1 & SW2)	OPEN	OPEN	OPEN	
V_{OUT}	Output Voltage Swing (2.0 pF Load)				V_{pp}
	Output Frequency 12.5–350 MHz (Note 1)	0.6	0.80	–	
	Output Frequency 350–400 MHz (Note 2)	0.5	0.70	–	
	Output Frequency 400–450 MHz (Note 3)	0.4	0.55	–	
	Output Frequency 450–550 MHz (Note 4)	0.3	0.45	–	
V_{IN}	Input Voltage Sensitivity				mVpp
	250–1100 MHz	100	–	1000	
	100–250 MHz	400	–	1000	

1. Input frequency 1.1 GHz, ± 8 , minimum output frequency of 12.5 MHz.

2. Input frequency 700–800 MHz, ± 2 .

3. Input frequency 800–900 MHz, ± 2 .

4. Input frequency 900–1100 MHz, ± 2 .

ORDERING INFORMATION

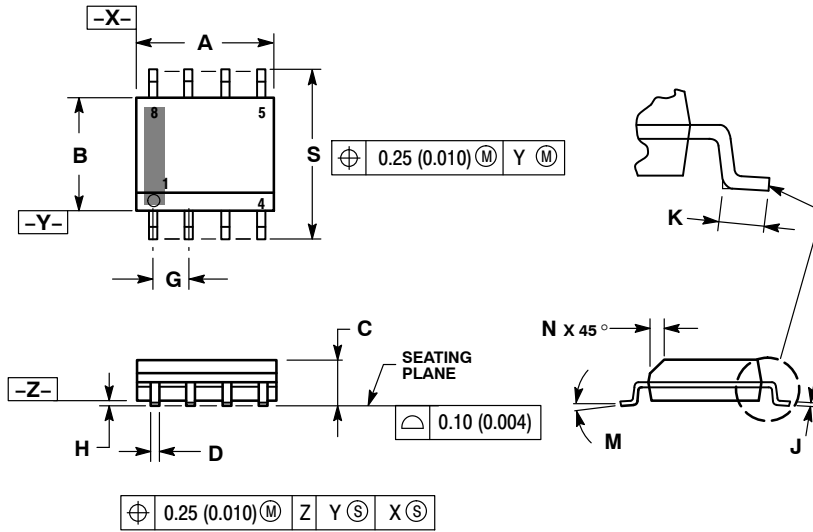
Device	Package	Shipping [†]
MC12093D	SOIC–8	98 Units / Rail
MC12093DG	SOIC–8 (Pb–Free)	98 Units / Rail
MC12093DR2	SOIC–8	2500 / Tape & Reel
MC12093DR2G	SOIC–8 (Pb–Free)	2500 / Tape & Reel
MC120932MNR4	DFN8	1000 / Tape & Reel
MC12093MNR4G	DFN8 (Pb–Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AG

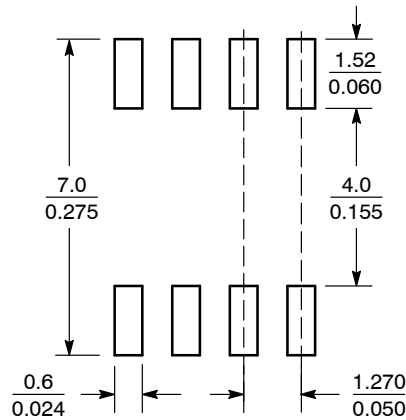


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



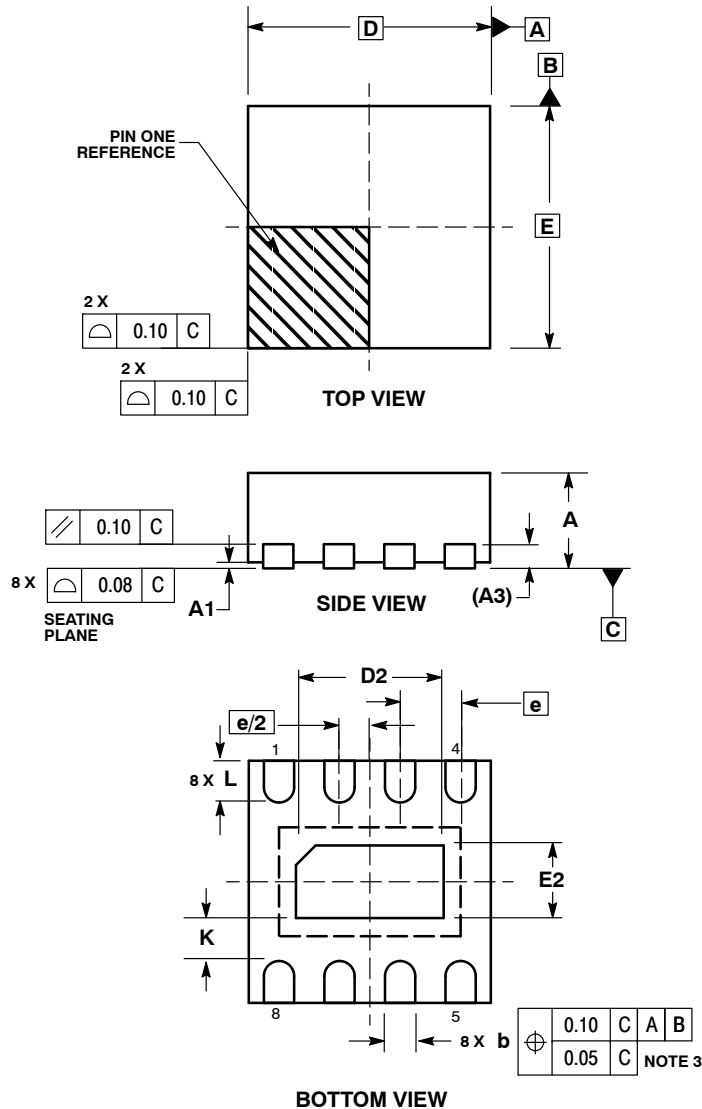
SCALE 6:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

DFN8
CASE 506AA-01
ISSUE C




NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.20	0.30
D	2.00	BSC
D2	1.10	1.30
E	2.00	BSC
E2	0.70	0.90
e	0.50	BSC
K	0.20	---
L	0.25	0.35

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